



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Grigg et al.

**Serial No.:** 10/688,354

**Filed:** October 17, 2003

**For:** THICK SOLDER MASK FOR  
CONFINING ENCAPSULANT MATERIAL  
OVER SELECTED LOCATIONS OF A  
SUBSTRATE AND ASSEMBLIES  
INCLUDING THE SOLDER MASK

**Confirmation No.:** 2306

**Examiner:** C. Wilson

**Group Art Unit:** 2891

**Attorney Docket No.:** 2269-5216.1US  
(99-0507.01/US)

**Notice of Allowance Mailed:**

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**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the specification** begin on page 3 of this paper;

**Amendments to the Abstract** appear on page 7 of this paper;

**Amendments to the claims** are set forth in the listing of the claims that begins on page 8 of this paper;

**Corrections to the drawings** are summarized on page 11 of this paper, with replacement sheets and annotated sheets showing the corrections enclosed herewith; and

**Remarks** start at page 12 of this paper.